

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---------------------------------|---------------------|
| 1 | 4 | 6211094.URPN. | USPAT | 2004/07/11 12:30 |
| 2 | 5 | ("3627569" "5131752" "5318632" "5800616" "6054181").PN. | USPAT | 2004/07/11 12:36 |
| 3 | 71 | 5131752.URPN. | USPAT | 2004/07/11 12:43 |
| 4 | 4 | 6211094.URPN. | USPAT | 2004/07/11 12:51 |
| 5 | 5 | ("3627569" "5131752" "5318632" "5800616" "6054181").PN. | USPAT | 2004/07/11 12:54 |
| 6 | 17 | 5503707.URPN. | USPAT | 2004/07/11 13:03 |
| 7 | 4 | ("4198261" "5131752" "5160576" "5270222").PN. | USPAT | 2004/07/11 13:04 |
| 8 | 0 | 5300313.URPN. | USPAT | 2004/07/11 13:08 |
| 9 | 0 | 5300313.URPN. | USPAT | 2004/07/11 13:09 |
| 10 | 5 | ("2726173" "4427711" "4466872" "5131752" "5204144").PN. | USPAT | 2004/07/11 13:09 |
| 11 | 8 | ("3158675" "4105338" "4649261" "4695162" "4698486" "4837603" "4850711" "4906844").PN. | USPAT | 2004/07/11 13:10 |
| 16 | 3525 | method with control with thickness with (film layer) | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:18 |
| 17 | 205 | (method with control with thickness with (film layer)) and determining and comparing | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:27 |
| 18 | 136 | ((method with control with thickness with (film layer)) and determining and comparing) and (wafer semiconductor) | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:26 |
| 19 | 86 | ((method with control with thickness with (film layer)) and determining and comparing) and (wafer semiconductor)) and adjusting | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:22 |
| 20 | 2024 | (method with control with thickness with (film layer)) and (wafer semiconductor) | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:26 |
| 21 | 1823 | adjusting same determining same comparing | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:38 |
| 22 | 2 | ((method with control with thickness with (film layer)) and (wafer semiconductor)) and (adjusting same determining same comparing) | USPAT; US-PGPUB; EPO; JPO | 2004/07/11 14:38 |